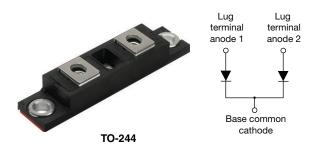


# **HEXFRED® Ultrafast Soft Recovery Diode, 280 A**



| PRODUCT SUMMARY                      |                           |  |  |  |  |
|--------------------------------------|---------------------------|--|--|--|--|
| I <sub>F(AV)</sub>                   | 280 A                     |  |  |  |  |
| $V_{R}$                              | 600 V                     |  |  |  |  |
| I <sub>F(DC)</sub> at T <sub>C</sub> | 149 A at 100 °C           |  |  |  |  |
| Package                              | TO-244 (TO-244AB)         |  |  |  |  |
| Circuit                              | Two diodes common cathode |  |  |  |  |

#### **FEATURES**

- Very low Q<sub>rr</sub> and t<sub>rr</sub>
- UL approved file E222165





• Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



#### **BENEFITS**

- Reduced RFI and EMI
- · Reduced snubbing

#### **DESCRIPTION**

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl<sub>F</sub>/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

| ABSOLUTE MAXIMUM RATINGS                         |                                   |   |             |       |  |
|--|-----------------------------------|---|-------------|-------|--|
| PARAMETER  | SYMBOL                            | TEST CONDITIONS                                       | MAX.        | UNITS |  |
| Cathode to anode voltage                         | V <sub>R</sub>                    |   | 600         | V     |  |
| Continuous forward current                       | ı                                 | T <sub>C</sub> = 25 °C                                | 292         |       |  |
| Continuous forward current                       | I <sub>F</sub>                    | T <sub>C</sub> = 100 °C                               | 149         | А     |  |
| Single pulse forward current                     | I <sub>FSM</sub>                  | Limited by junction temperature                       | 600         |       |  |
| Non-repetitive avalanche energy                  | E <sub>AS</sub>                   | $L = 100 \mu H$ , duty cycle limited by maximum $T_J$ | 2.2         | mJ    |  |
| Maximum power dissipation                        | ם                                 | T <sub>C</sub> = 25 °C                                | 657         | W     |  |
| Maximum power dissipation                        | $P_{D}$                           | T <sub>C</sub> = 100 °C                               | 263 VV      |       |  |
| Operating junction and storage temperature range | T <sub>J</sub> , T <sub>Stg</sub> |   | -55 to +150 | °C    |  |

| <b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                 |   |            |      |      |      |       |
|--|-----------------|---|------------|------|------|------|-------|
| PARAMETER  | SYMBOL          | TEST CONDITIONS                                 |            | MIN. | TYP. | MAX. | UNITS |
| Cathode to anode breakdown voltage   | V <sub>BR</sub> | I <sub>R</sub> = 100 μA                         |            | 600  | -    | -    |       |
|  |                 | I <sub>F</sub> = 105 A                          |            | -    | 1.33 | 1.8  | V     |
| Maximum forward voltage  | $V_{FM}$        | I <sub>F</sub> = 210 A                          | See fig. 1 | -    | 1.53 | 2.1  |       |
|  |                 | I <sub>F</sub> = 105 A, T <sub>J</sub> = 125 °C |            | -    | 1.22 | 1.64 |       |
| Maximum reverse leakage current  | I <sub>RM</sub> | T <sub>J</sub> = 125 °C, V <sub>R</sub> = 600 V | See fig. 2 | -    | 2.4  | 8    | mA    |
| Junction capacitance   | C <sub>T</sub>  | V <sub>R</sub> = 200 V                          | See fig. 3 | -    | 280  | 400  | pF    |
| Series inductance  | L <sub>S</sub>  | From top of terminal hole to mounting plane     |            | 1    | 5.0  | -    | nH    |



| <b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                          |  |                         |   |      |      |       |      |
|---|--------------------------|--|-------------------------|---|------|------|-------|------|
| PARAMETER   | SYMBOL                   | TEST CONDITIONS  |                         | MIN.  | TYP. | MAX. | UNITS |      |
| Reverse recovery time   |                          | $I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ |                         | -   | 39   | -    |       |      |
| See fig. 5  | t <sub>rr</sub>          | T <sub>J</sub> = 25 °C   |                         | -   | 92   | 140  | ns    |      |
|   |                          | T <sub>J</sub> = 125 °C  |                         | -   | 180  | 270  |       |      |
| Peak recovery current   | I <sub>RRM</sub>         | T <sub>J</sub> = 25 °C   |                         | -   | 9.3  | 17   | ^     |      |
| See fig. 6  |                          | IRRM   | T <sub>J</sub> = 125 °C | $I_F = 105 \text{ A}$<br>$dI_F/dt = 200 \text{ A/}\mu\text{s}$<br>$V_R = 200 \text{ V}$ | -    | 16   | 30    | A    |
| Reverse recovery charge   |                          |  | T <sub>J</sub> = 25 °C  |   | =    | 490  | 1200  | nC   |
| See fig. 7  |                          | T <sub>J</sub> = 125 °C  |                         | -   | 1400 | 4000 | IIC   |      |
| Peak rate of recovery current   | dI <sub>(rec)M</sub> /dt | dl /d+   | T <sub>J</sub> = 25 °C  |   | -    | 290  | -     | A/µs |
| See fig. 8  |                          | T <sub>J</sub> = 125 °C  |                         | -   | 200  | -    | AvμS  |      |

| THERMAL - MECHANICAL SPECIFICATIONS            |             |                                   |          |      |          |                     |
|--|-------------|-----------------------------------|----------|------|----------|---------------------|
| PARAMETER                                      |             | SYMBOL                            | MIN.     | TYP. | MAX.     | UNITS               |
| Maximum junction and storage temperature range |             | T <sub>J</sub> , T <sub>Stg</sub> | -55      | -    | 150      | °C                  |
| Thermal resistance, junction to case           | per leg     | В                                 | -        | -    | 0.19     | °C/W<br>K/W         |
|  | per module  | R <sub>thJC</sub>                 | -        | -    | 0.095    |                     |
| Typical thermal resistance, case to heatsink   |             | R <sub>thCS</sub>                 | -        | 0.10 | -        |                     |
| W-:-L1   |             |                                   | -        | 68   | -        | g                   |
| Weight   |             |                                   | -        | 2.4  | -        | OZ.                 |
| Mounting torque (1)                            |             |                                   | 30 (3.4) | -    | 40 (4.6) |                     |
| Mounting torque (1)                            | center hole |                                   | 12 (1.4) | -    | 18 (2.1) | N ⋅ m<br>(lbf ⋅ in) |
| Terminal torque                                |             |                                   | 30 (3.4) | -    | 40 (4.6) | ] (                 |
| Vertical pull                                  |             |                                   | -        | -    | 80       | llef in             |
| 2" lever pull                                  |             |                                   | -        | -    | 35       | lbf ∙ in            |

#### Note

<sup>(1)</sup> Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached.

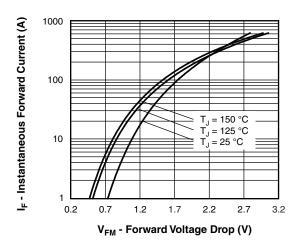


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

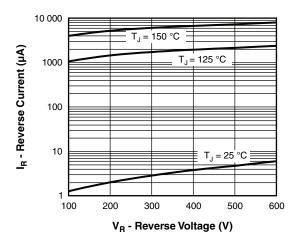


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

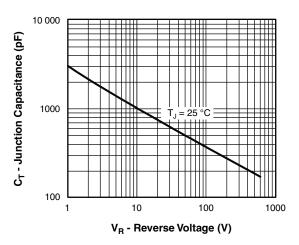


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

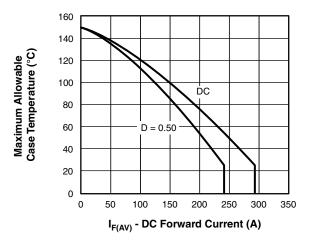


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

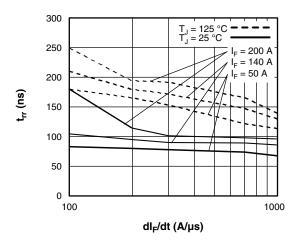


Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$  (Per Leg)

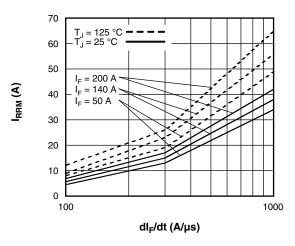


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

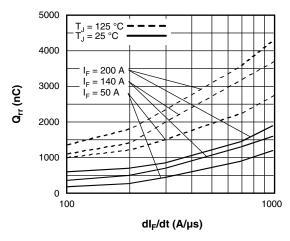


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

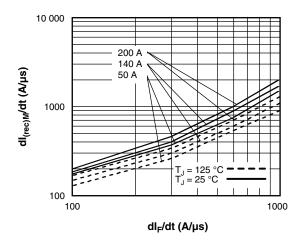


Fig. 8 - Typical  $dI_{(rec)M}/dt$  vs.  $dI_F/dt$  (Per Leg)

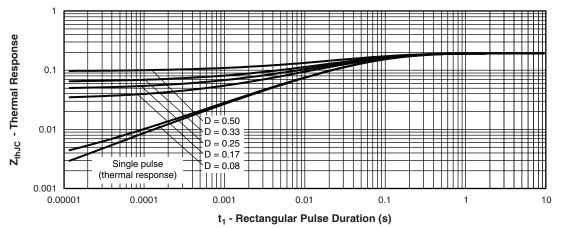


Fig. 9 - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

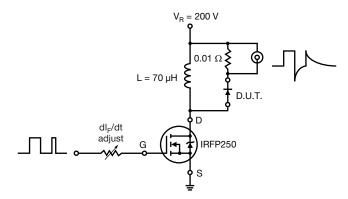
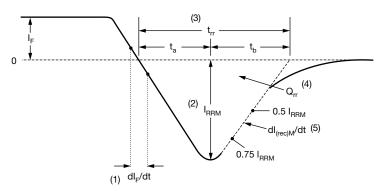


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $\boldsymbol{I}_{\text{RRM}}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_{r}$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\rm Q_{rr}$  area under curve defined by  $\rm t_{rr}$  and  $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5)  $dI_{(rec)M}/dt$  - peak rate of change of current during  $t_{b}$  portion of  $t_{rr}$ 

Fig. 11 - Reverse Recovery Waveform and Definitions



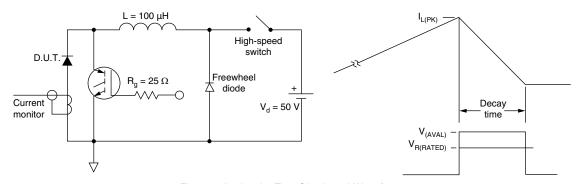
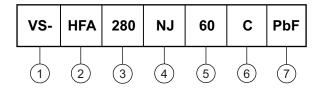


Fig. 12 - Avalanche Test Circuit and Waveforms

#### **ORDERING INFORMATION TABLE**

#### **Device code**



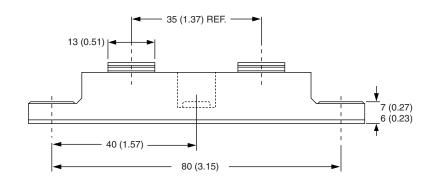
- 1 Vishay Semiconductors product
- 2 HEXFRED® family, electron irradiated
- 3 Average current rating
- **4** NJ = TO-224
- 5 Voltage rating (600 V)
- 6 C = Common cathode
- 7 Lead (Pb)-free

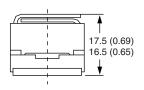
| LINKS TO RELATED DOCUMENTS |                          |  |  |  |
|----------------------------|--------------------------|--|--|--|
| Dimensions                 | www.vishay.com/doc?95021 |  |  |  |

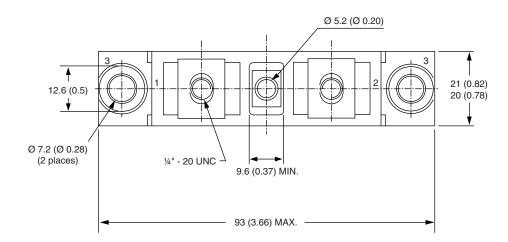


### **TO-244**

### **DIMENSIONS** in millimeters (inches)









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